

L Number	Hits	Search Text	DB	Time stamp
-	337714	semiconductor with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:34
-	13822	(semiconductor with substrate) and (silicon near3 source silicon adj containing si adj containing silicon adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:37
-	13822	(semiconductor with substrate) and (silicon near3 source silicon adj containing si adj containing silicon adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:35
-	337714	semiconductor with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:35
-	13822	((semiconductor with substrate) and (silicon near3 source silicon adj containing si adj containing silicon adj material)) and (semiconductor with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:36
-	4226	((semiconductor with substrate) and (silicon near3 source silicon adj containing si adj containing silicon adj material)) and (semiconductor with substrate)) and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:36
-	851	barrier with (silicon near3 source silicon adj containing si adj containing silicon adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:38
-	396	barrier near5 (silicon near3 source silicon adj containing si adj containing silicon adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:39
-	342525	('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:42
-	851	(barrier with (silicon near3 source silicon adj containing si adj containing silicon adj material)) or (barrier near5 (silicon near3 source silicon adj containing si adj containing silicon adj material))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:43
-	452	((semiconductor with substrate) and (silicon near3 source silicon adj containing si adj containing silicon adj material)) and (semiconductor with substrate)) and barrier and ((barrier with (silicon near3 source silicon adj containing si adj containing silicon adj material)) or (barrier near5 (silicon near3 source silicon adj containing si adj containing silicon adj material)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:43

-	4	(((NH3' N2' O3' N2O' NO') with (gas\$2 reactive react\$4)) and ((((semiconductor with substrate) and (silicon near3 source silicon adj containing si adj containing silicon adj material)) and (semiconductor with substrate)) and barrier) and ((barrier with (silicon near3 source silicon adj containing si adj containing silicon adj material)) or (barrier near5 (silicon near3 source silicon adj containing si adj containing silicon adj material)))))) and silazane	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 16:44
-	102	(((NH3' N2' O3' N2O' NO') with (gas\$2 reactive react\$4)) and ((((semiconductor with substrate) and (silicon near3 source silicon adj containing si adj containing silicon adj material)) and (semiconductor with substrate)) and barrier) and ((barrier with (silicon near3 source silicon adj containing si adj containing silicon adj material)) or (barrier near5 (silicon near3 source silicon adj containing si adj containing silicon adj material))))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 17:13

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(4) (('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)) and (((semiconductor with...
 (102) (('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)) and (((semiconductor wit...

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1 2 3 4 5 6 7 8 9 10 11 12

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20030045096 A1	20030306	24	Semiconductor device manufacturing method	438/687	
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20030022507 A1	20030130	22	CVD TiSiN barrier for copper integration	438/706	
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20030022487 A1	20030130	23	Barrier formation using novel sputter-deposition method	438/642	438/649; 438/655
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20020197856 A1	20021226	26	Method of forming a barrier film and method of forming wiring structure an	438/652	257/E29.157
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20020197849 A1	20021226	20	Very low dielectric constant plasma-enhanced CVD films	438/633	
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20020195643 A1	20021226	29	Semiconductor device and method for producing the same	257/310	257/E29.164; 257/E29.165
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20020180028 A1	20021205	19	Silicon source reagent compositions, and method of making and using sam	257/700	
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20020173137 A1	20021121	17	Combined barrier layer and seed layer	438/618	438/628; 438/637
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20020146511 A1	20021010	59	Chemisorption technique for atomic layer deposition	427/248.1	
10	<input type="checkbox"/>	<input type="checkbox"/>	US 20020144786 A1	20021010	59	Substrate temperature control in an ALD reactor	156/345.51	118/723E; 118/728;
11	<input type="checkbox"/>	<input type="checkbox"/>	US 20020144657 A1	20021010	62	ALD reactor employing electrostatic chuck	118/723E	118/728; 427/248.1;
12	<input type="checkbox"/>	<input type="checkbox"/>	US 20020144655	20021010	59	Gas valve system for a reactor	118/715	

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4) (((('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)) and ((((((semiconductor with...
(102) (((('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)) and ((((((semiconductor wit...

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
13	<input type="checkbox"/>	<input type="checkbox"/>	US 20020142585 A1	20021003	21	Very low dielectric constant plasma-enhanced CVD films	438/633	
14	<input type="checkbox"/>	<input type="checkbox"/>	US 20020142538 A1	20021003	12	Process for fabricating RuSixOy-containing adhesion layers	438/238	
15	<input type="checkbox"/>	<input type="checkbox"/>	US 20020140890 A1	20021003	18	Liquid crystal display component and transparent conductive substrate suite	349/122	349/158
16	<input type="checkbox"/>	<input type="checkbox"/>	US 20020132374 A1	20020919	22	Method for controlling deposition of dielectric films	438/3	
17	<input type="checkbox"/>	<input type="checkbox"/>	US 20020125516 A1	20020912	12	RuSixOy-containing adhesion layers and process for fabricating the same	257/295	
18	<input type="checkbox"/>	<input type="checkbox"/>	US 20020096726 A1	20020725	11	Semiconductor device and manufacturing method thereof	257/384	
19	<input type="checkbox"/>	<input type="checkbox"/>	US 20020076881 A1	20020620	12	RuSixOy-containing adhesion layers and process for fabricating the same	438/250	
20	<input type="checkbox"/>	<input type="checkbox"/>	US 20020076508 A1	20020620	60	Varying conductance out of a process region to control gas flux in a	427/569	427/255.28; 427/377
21	<input type="checkbox"/>	<input type="checkbox"/>	US 20020076507 A1	20020620	59	Process sequence for atomic layer deposition	427/569	427/248.1
22	<input type="checkbox"/>	<input type="checkbox"/>	US 20020076490 A1	20020620	60	Variable gas conductance control for a process chamber	427/248.1	118/504; 118/715
23	<input type="checkbox"/>	<input type="checkbox"/>	US 20020076481 A1	20020620	59	Chamber pressure state-based control for a reactor	427/8	427/248.1
24	<input type="checkbox"/>	<input type="checkbox"/>	US 20020074577	20020620	12	RuSixOy-containing adhesion layers	257/250	

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(4) (('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)) and (((semiconductor with...
(102) (('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)) and (((semiconductor wil...

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
49	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6369871 B1	20020409	17	Liquid crystal display component and transparent conductive substrate suite	349/158	428/1.1;
50	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6329286 B1	20011211	10	Methods for forming conformal iridium layers on substrates	438/650	428/447;
51	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6323081 B1	20011127	15	Diffusion barrier layers and methods of forming same	438/239	257/E21.011;
52	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6297173 B1	20011002	21	Process for forming a semiconductor device	438/778	427/252;
53	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6284665 B1	20010904	18	Method for controlling the shape of the etch front in the etching of polysil	438/710	438/253;
54	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6246105 B1	20010612	21	Semiconductor device and manufacturing process thereof	257/640	438/396;
55	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6245648 B1	20010612	10	Method of forming semiconducting materials and barriers	438/482	257/E21.193;
56	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6235456 B1	20010522	16	Graded anti-reflective barrier films for ultra-fine lithography	430/512	257/E21.433;
57	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6204172 B1	20010320	15	Low temperature deposition of barrier layers	438/653	257/E21.312;
58	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6194304 B1	20010227	20	Semiconductor device and method of fabricating the same	438/618	257/E21.396;
59	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6180469 B1	20010130	8	Low resistance salicide technology with reduced silicon consumption	438/299	257/637;
60	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6171945 B1	20010109	25	CVD nanoporous silica low dielectric	438/622	257/641;

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(4) (('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)) and (((semiconductor with...
 (102) (('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)) and (((semiconductor witl...
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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
61	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6162744 A	20001219	10	Method of forming capacitors having high-K oxygen containing capacitor d	438/785	257/E21.008; 438/240;
62	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6151347 A	20001121		Laser diode and method of fabrication thereof	372/45	372/96
63	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6137176 A	20001024		Semiconductor device and method of fabricating the same	257/751	257/750; 257/752;
64	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6107184 A	20000822		Nano-porous copolymer films having low dielectric constants	438/623	257/E21.259; 427/255.6;
65	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6107182 A	20000822		Semiconductor device and method of fabricating the same	438/618	257/E21.165; 257/E21.576;
66	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6103456 A	20000815		Prevention of photoresist poisoning from dielectric antireflective coating i	430/317	257/E21.029; 257/E21.257;
67	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6074954 A	20000613		Process for control of the shape of the etch front in the etching of polysili	438/710	257/E21.312; 257/E21.396;
68	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6069093 A	20000530		Process of forming metal films and multi layer structure	438/761	257/E21.165; 257/E21.17;
69	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5972804 A	19991026		Process for forming a semiconductor device	438/786	257/E21.193; 257/E21.433;
70	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5972765 A	19991026		Use of deuterated materials in semiconductor processing	438/308	257/E21.165; 257/E21.193;
71	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5926734 A	19990720		Semiconductor structure having a titanium barrier layer	438/627	257/E21.584; 438/628;
72	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5925494 A	19990720		Vapor deposition of polymer films	430/270.1	427/488;

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
73	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5874355 A	19990223		Method to prevent volcane effect in tungsten plug deposition	438/627	257/E21.584; 257/E21.585;
74	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5837598 A	19981117		Diffusion barrier for polysilicon gate electrode of MOS device in integrate	438/532	257/E21.197; 257/E29.154;
75	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5834804 A	19981110		Ferroelectric structure including MgTiO ₃ sub 3 passivation	257/295	257/303; 257/632;
76	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5695815 A	19971209		Metal carboxylate complexes for formation of metal-containing films o	427/226	257/E21.009; 257/E21.011;
77	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5563102 A	19961008		Method of sealing integrated circuits	438/614	257/E23.167; 438/702;
78	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5543634 A	19960806		Method of forming semiconductor materials and barriers	257/54	257/475; 257/55
79	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5539551 A	19960723		LCD TFT drain and source electrodes having ohmic barrier, prim	349/42	257/59; 257/E27.111;
80	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5472912 A	19951205		Method of making an integrated circuit structure by using a non-cond	438/643	257/E21.162; 257/E21.295;
81	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5470784 A	19951128		Method of forming semiconducting materials and barriers using a multiple	438/61	118/719; 427/569;
82	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5268590 A	19931207		CMOS device and process	257/764	257/371; 257/377;
83	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5073804 A	19911217		Method of forming semiconductor materials and barriers	257/30	136/255; 136/258;
84	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5064691 A	19911112		Gas phase borosiliconization of	427/252	148/279; 157/668

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
92	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4681652 A	19870721		Manufacture of polycrystalline silicon	117/88	117/101; 117/102;
93	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4678731 A	19870707		Electrophotographic photosensitive member having barrier layer comprisi	430/65	430/945
94	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4587710 A	19860513		Method of fabricating a Schottky barrier field effect transistor	438/571	148/DIG.140; 257/280;
95	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4470189 A	19840911		Process for making polycide structures	438/301	148/DIG.84; 204/192.32;
96	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4430153 A	19840207		Method of forming an RIE etch barrier by in situ conversion of a silic	438/705	204/192.32; 257/E21.256;
97	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4377031 A	19830322		Method of making Schottky barrier diode by selective beam-crystallized	438/487	117/904; 148/DIG.46;
98	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4328258 A	19820504		Method of forming semiconducting materials and barriers	118/50.1	118/723E; 118/723VE;
99	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4303467 A	19811201		Process and gas for treatment of semiconductor devices	438/720	204/192.32; 252/79.1;
100	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4226897 A	19801007		Method of forming semiconducting materials and barriers	438/96	136/258; 204/164;
101	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4214315 A	19800722		Method for fabricating vertical NPN and PNP structures and the resulting	257/517	257/516; 257/577;
102	<input checked="" type="checkbox"/>	<input type="checkbox"/>	EP 437307 A	19910717		High resistance poly:silicon load resistor - comprises structure includin		

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BRS: 8 and (barrier with silicon)

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Active

- L5: (13822) (semiconductor with substrate) and (silicon near3 source silicon adj containing s...
- L6: (337714) semiconductor with substrate
- L7: (13822) 5 and 6
- L8: (4226) 7 and barrier
- L9: (851) barrier with (silicon near3 source silicon adj containing si adj containing silicon...
- L10: (396) barrier near5 (silicon near3 source silicon adj containing si adj containing silic...
- L11: (342525) ('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)
- L12: (851) 9 or 10
- L13: (452) 8 and 12
- L15: (4) 14 and silazane
- L14: (102) 11 and 13

Failed

- (0) ('NH3' 'N2' 'O3' 'N2O' 'NO') with (gas\$2 reactive react\$4)

11 and 13

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20030045096 A1	20030306	24	Semiconductor device manufacturing method	438/687	
2	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030022507 A1	20030130	22	CVD TiSiN barrier for copper integration	438/706	
3	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030022487 A1	20030130	23	Barrier formation using novel sputter-deposition method	438/642	438/649; 438/655
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20020197856 A1	20021226	26	Method of forming a barrier film and	438/652	257/E29.157

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- (919) computer adj system with semiconductor
- (450) (computer adj system with semiconductor) and proces
- (427) ((computer adj system with semiconductor) and proce
- (216) (((computer adj system with semiconductor) and proc
- (53) transistor and (((computer adj system with semiconduc
- (1) "5889307".PN.
- (1) "6034433".PN.
- (349) (((computer adj system with semiconductor) and proc
- (349) (((computer adj system with semiconductor) and proc
- (104) (((computer adj system with semiconductor) and proc
- (1) ("5696917").PN.

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USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM

☒ Plurals

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(((computer adj system with semiconductor) and processor) and memory) and (data adj bus system adj bus 'ROM' 'RAM')) and transistor

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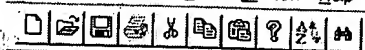
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- ☒ L2: (919) computer adj system with semiconductor
- ☒ L3: (450) 2 and processor
- ☒ L4: (427) 3 and memory
- ☒ L5: (216) 4 and (data adj bus system adj bus)
- ☒ L6: (53) transistor and 5
- ☒ L7: (1) "5889307".PN.
- ☒ L8: (1) "6034433".PN.
- ☒ L9: (349) 4 and (data adj bus system adj bus 'RAM' 'ROM')
- ☒ L10: (349) 4 and (data adj bus system adj bus 'ROM' 'RAM')
- ☒ L11: (104) 10 and transistor

 Search
DBs USPAT☒ PluralsDefault operator: OR☒ Highlight all hit terms initially**10 and transistor**

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6342723 B1	20020129	12	Integrated circuit having temporary conductive path structure and method	257/529	257/355;
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6339817 B1	20020115	122	Semiconductor memory including main and sub memory portions havin	711/165	257/546
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6327639 B1	20011204	20	Method and apparatus for storing location identification information wit	711/103	365/189.04;
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6323867 B1	20011127	17	Parsing graphics data structure into command and data memes	345/522	365/230.03;
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6323076 B1	20011127	10	Integrated circuit having temporary conductive path structure and method	438/215	156/165;
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6320782 B1	20011120	272	Semiconductor memory device and various systems mounting them	365/145	156/206;
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6320453 B1	20011120	8	Method and circuit for lowering standby current in an integrated circuit	327/534	710/52
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6313658 B1	20011106	11	Device and method for isolating a short-circuited integrated circuit (IC)	324/765	438/281;
9	<input type="checkbox"/>	<input type="checkbox"/>	US 6307780 B1	20011023	27	Semiconductor non-volatile storage	365/185.13	438/601;
								365/149
								324/769
								365/185.11

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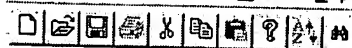
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- ☒ L1: (0) semiconductor with (computer adj system)
- ☒ L2: (911) semiconductor with (computer adj system)
- ☒ L3: (28) semiconductor with ((computer adj system) and processor and memory and bus)
- ☒ L4: (798) 2 and memory
- ☒ L5: (798) 2 and memory
- ☒ L6: (424) 4 and processor
- ☒ L7: (125) 6 and (data adj bus)
- ☒ L8: (59) 7 and 'ROM'
- ☒ L9: (25) 8 and memory adj cell
- ☒ L10: (219) semiconductor same ((computer adj system) and processor and memory and bus)
- ☒ L11: (49) transistor same ((computer adj system) and processor and memory and bus)

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DBs U Plurals

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transistor same
((computer adj system)
and processor and
memory and bus)

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6348917 B1	20020219	19	Dynamic switching of texture mip-maps based on depth	345/418	345/582
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6341183 B1	20020122	16	Graphical user interface for image acquisition and processing	382/276	345/762; 382/305
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6327178 B1	20011204	9	Programmable circuit and its method of operation	365/177	326/35; 326/44;
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6326652 B1	20011204	21	CMOS imager with a self-aligned buried contact	257/231	257/232; 257/233;
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6301172 B1	20011009	20	Gate voltage testkey for isolation transistor	365/201	365/208
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6291280 B1	20010918	19	CMOS imager cell having a buried contact and method of fabrication	438/199	438/200; 438/231;